

Products Information

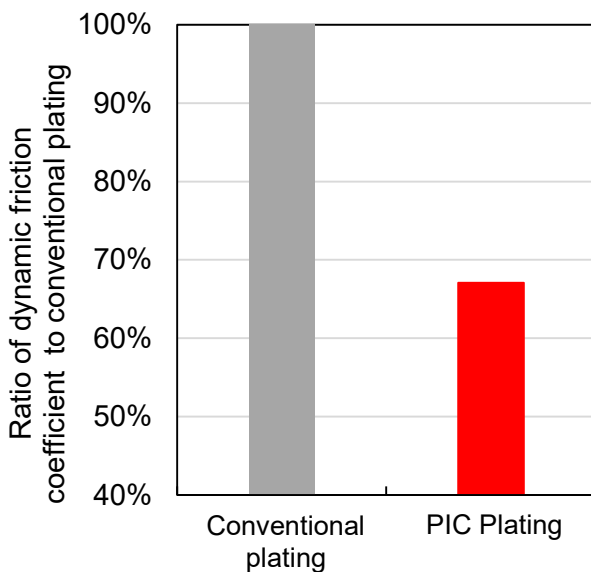
Features

- Low insertion/removal force of connectors, dynamic friction coefficient is up to around 30% lower than conventional reflow Sn plating (Conventional plating)
- Large amounts of Tin (Sn) are left between Cu-Sn intermetallic compound (IMC), achieving excellent electrical connection reliability
- Available for various copper and copper alloys, such as Cu-Mg-based copper alloy, MSP series

Application examples

- Small terminals for automotive multipole connectors

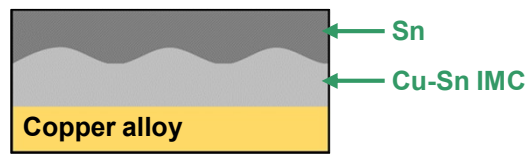
Dynamic friction coefficient



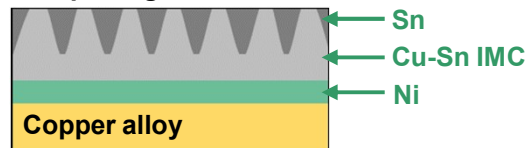
Structure of plating

- Cu-Sn IMC is precisely controlled to form columnar grains exposed homogeneously to the surface
- Large amounts of Sn are left between Cu-Sn IMC grains

Conventional plating

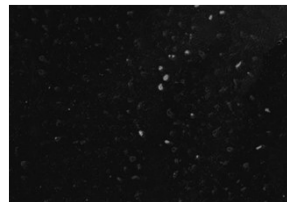


PIC plating

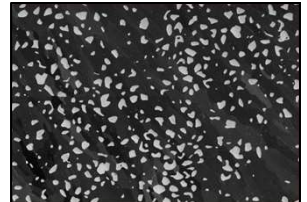


Cross sections of plating

Conventional plating



PIC plating



The white parts are Cu-Sn IMC

Surface images of plating

Heat resistance

